

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-14 (canceled).

Claim 15 (new): A composite ceramic substrate comprising:
a ceramic substrate including a surface-mounted component mounted thereon;
at least one wiring pattern disposed in the ceramic substrate;
at least one external terminal electrode connecting the at least one wiring pattern to a surface electrode of a motherboard;
at least one convex leg portion made of resin and arranged on the ceramic substrate such that an end surface thereof supports the external terminal electrode; and
a via-hole conductor provided in the at least one convex leg portion and connecting the at least one external terminal electrode to the at least one wiring pattern.

Claim 16 (new): The composite ceramic substrate according to claim 15, wherein the surface-mounted component is mounted on at least one of a first main surface and a second main surface of the ceramic substrate and the convex leg portion is disposed on the second main surface of the ceramic substrate.

Claim 17 (new): The composite ceramic substrate according to claim 16, wherein the convex leg portion is disposed at a periphery of the second main surface of the ceramic substrate.

Claim 18 (new): The composite ceramic substrate according to claim 17, wherein the at least one external terminal electrode includes a plurality of external terminal electrodes supported by the end surface of the convex leg portion.

Claim 19 (new): The composite ceramic substrate according to claim 18, wherein none of the plurality of external terminal electrodes are disposed at corners of the second main surface of the ceramic substrate.

Claim 20 (new): The composite ceramic substrate according to claim 19, wherein the corners are disposed at a height that is lower than a height at which the external terminal electrodes are disposed.

Claim 21 (new): The composite ceramic substrate according to claim 16, wherein at least one convex leg portions include a plurality of convex leg portions, and the surface-mounted component is mounted between the plurality of convex leg portions on the second main surface.

Claim 22 (new): The composite ceramic substrate according to claim 21, wherein the surface-mounted component is coated with resin that is the same as the resin from which the plurality of convex leg portions are made.

Claim 23 (new): The composite ceramic substrate according to claim 22, wherein a round portion is provided between the plurality of convex leg portions and the resin coating the surface-mounted component.

Claim 24 (new): The composite ceramic substrate according to claim 22, wherein the surface of the resin coating the surface-mounted component includes a slit.

Claim 25 (new): The composite ceramic substrate according to claim 15, wherein an edge of the convex leg portion has a rounded shape.

Claim 26 (new): The composite ceramic substrate according to claim 15, wherein the via-hole conductor is made of a flexible conductive resin.

International Application No.: PCT/JP2005/012403

U.S. Patent Application No.: Unknown

June 14, 2006

Page 7 of 8

Claim 27 (new): The composite ceramic substrate according to claim 15, wherein the ceramic substrate is a multilayer ceramic substrate including a plurality of laminated low temperature co-fired ceramic layers.

Claim 28 (new): The composite ceramic substrate according to claim 15, wherein the surface-mounted component includes an array of external terminal electrodes.